

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Original) A shadow mask for fabricating a flat display, comprising:  
a first substrate having a plurality of first via holes;  
a second substrate on the first substrate, the second substrate having a plurality of second via holes;  
wherein the first via holes and the second via holes are arranged to overlap with each other, and the second via hole has a diameter greater than a diameter of the first via hole.
2. (Original) The shadow mask as claimed in claim 1, wherein the second substrate has a thickness thicker than a thickness of the first substrate.
3. (Original) The shadow mask as claimed in claim 2, wherein the first substrate is 1 - 100 $\mu$ m thick, and the second substrate is 5 - 1000 $\mu$ m thick.
4. (Original) The shadow mask as claimed in claim 1, wherein the first via hole and the second via hole have a 1 - 1000 $\mu$ m diametric difference.

5. (Original) The shadow mask as claimed in claim 1, wherein a plurality of the first via holes are arranged on every column, and one second via hole is arranged on every column.

6. (Original) The shadow mask as claimed in claim 5, wherein the first and second via holes have a form selected from a circle, a polygon, and stripe.

7. (Original) The shadow mask as claimed in claim 1, further comprising a bridge formed on the first substrate between adjacent first via holes.

8. (Original) The shadow mask as claimed in claim 7, wherein the bridge has a thickness the same with the thickness of the second substrate.

9. (Original) The shadow mask as claimed in claim 7, wherein the bridge is formed across the second via hole.

10. (Currently Amended) ~~A~~ The shadow mask for fabricating a flat display as claimed in claim 1, further comprising:

~~a first substrate having a plurality of first via holes;~~

~~a second substrate on the first substrate, the second substrate having a plurality of second via holes;~~

a third substrate on the second substrate, the third substrate having a plurality of third via holes;

wherein the first, second, and third via holes are arranged to overlap with one another, the second via hole has a diameter greater than a diameter of the first via hole, and the third via hole has a diameter greater than the diameter of the second via hole.

11. (Original) The shadow mask as claimed in claim 10, wherein the second substrate has a thickness thicker than a thickness of the first or third substrate.

12. (Original) The shadow mask as claimed in claim 11, wherein the first or third substrate is 1 - 100 $\mu$ m thick, and the second substrate is 5 - 1000 $\mu$ m thick.

13. (Original) The shadow mask as claimed in claim 10, wherein the first via hole and the second via hole, or the second via hole and the third via hole, have a 1 - 1000 $\mu$ m diametric difference.

14. (Original) The shadow mask as claimed in claim 10, wherein a plurality of the first via holes are arranged on every column, and one second or third via hole is arranged on every column.

15. (Original) The shadow mask as claimed in claim 14, wherein the first, second, and third via holes have forms selected from a circle, a polygon, and stripe.

16. (Original) The shadow mask as claimed in claim 10, further comprising a bridge formed on the first substrate between adjacent first via holes.

17. (Original) The shadow mask as claimed in claim 16, wherein the bridge has a thickness the same with the thickness of the second substrate.

18. (Original) The shadow mask as claimed in claim 16, wherein the bridge is formed across the second via hole.